

Product Change Notification - RMES-28ILIX343

Date: 03 Jul 2017
Product Category: 8-bit PIC Microcontrollers
Notification subject: CCB 3012 Initial Notice: Qualification of gold (Au) bond wire as secondary wire material for selected Atmel devices available in 14L SOIC package at MMT assembly site.
Notification text: **PCN Status:**
 Initial notification

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of gold (Au) bond wire as secondary wire material for selected Atmel devices available in 14L SOIC package at MMT assembly site.

Pre Change:

Using palladium coated copper with gold flash (CuPdAu) bond wire.

Post Change:

Using palladium coated copper with gold flash (CuPdAu) bond wire or gold (Au) bond wire.

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	MMT	MMT
Wire material	CuPdAu	CuPdAu or Au
Die attach material	8390A	8390A
Molding compound material	G600	G600
Lead frame material	CDA194	CDA194

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve on-time delivery performance by qualifying gold (Au) bond wire for selected Atmel devices at MMT assembly site.

Change Implementation Status:

In Progress

Estimated Qualification Completion Date:

August 2017

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	July 2017					->	August 2017				
Workweek	27	28	29	30	31		31	32	33	34	35
Initial PCN Issue Date	X										
Qualification Report Availability									X		
Final PCN Issue Date									X		

Method to Identify Change:
Traceability code

Qualification Plan:
Please open the attachments included with this PCN labeled as PCN_#_Qual Plan.

Revision History:
July 03, 2017: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

- [PCN_RMES-28ILIX343_Affected_CPN.pdf](#)
- [PCN_RMES-28ILIX343_Qual_Plan.pdf](#)
- [PCN_RMES-28ILIX343_Affected_CPN.xlsx](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Number (CPN)

PCN_RMES-28ILIX343
CATALOG_PART_NBR
ATTINY24A-SSF
ATTINY24A-SSFR
ATTINY24A-SSU
ATTINY24A-SSUR
ATTINY44A-SSF
ATTINY44A-SSFR
ATTINY44A-SSU
ATTINY44A-SSUR
ATTINY84A-SSF
ATTINY84A-SSFR
ATTINY84A-SSU
ATTINY84A-SSUR